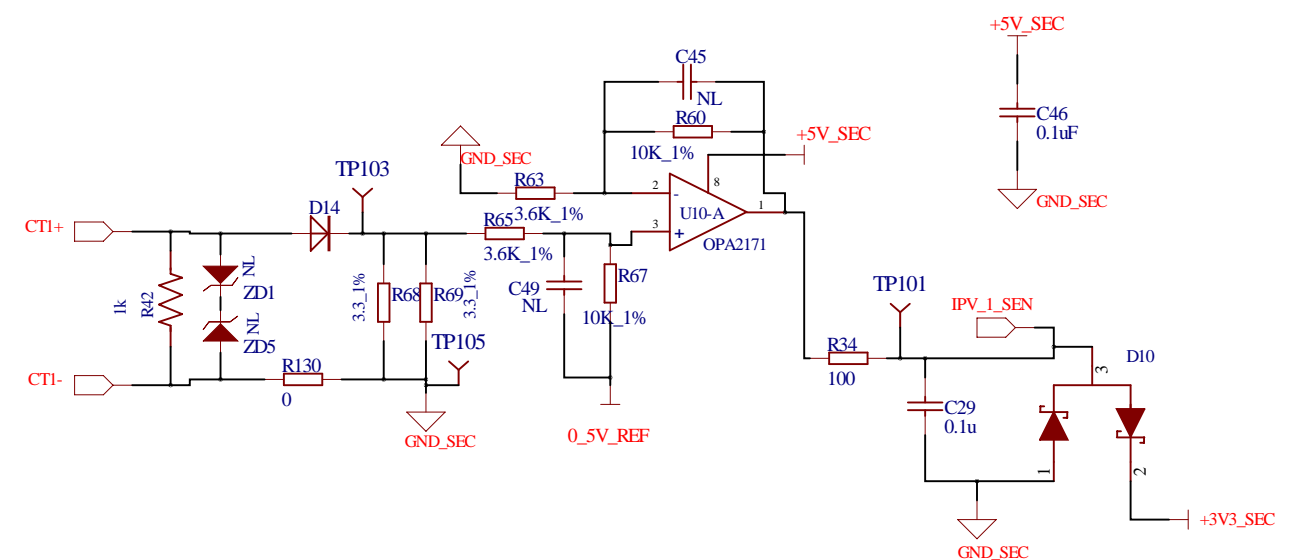
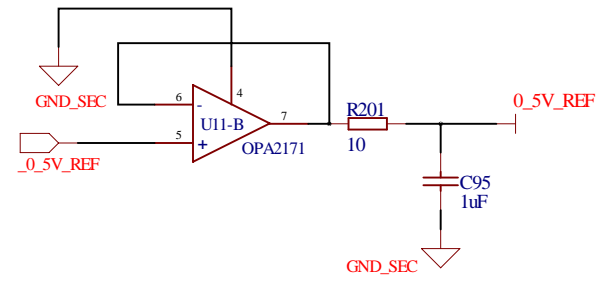
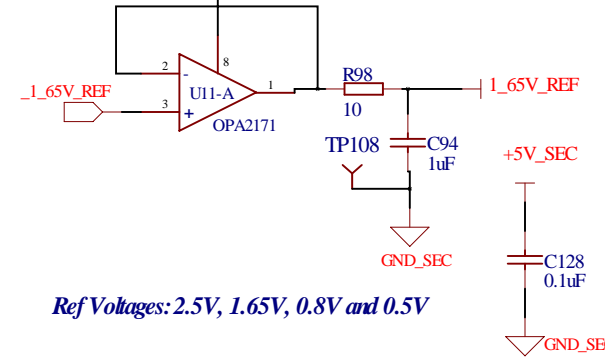
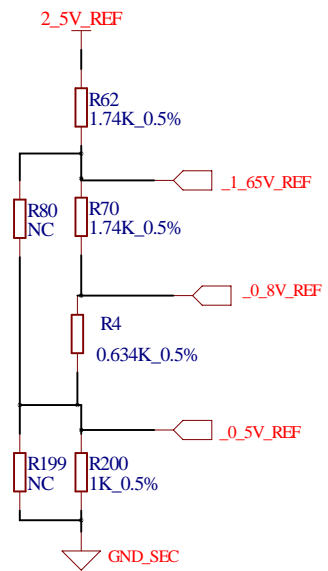
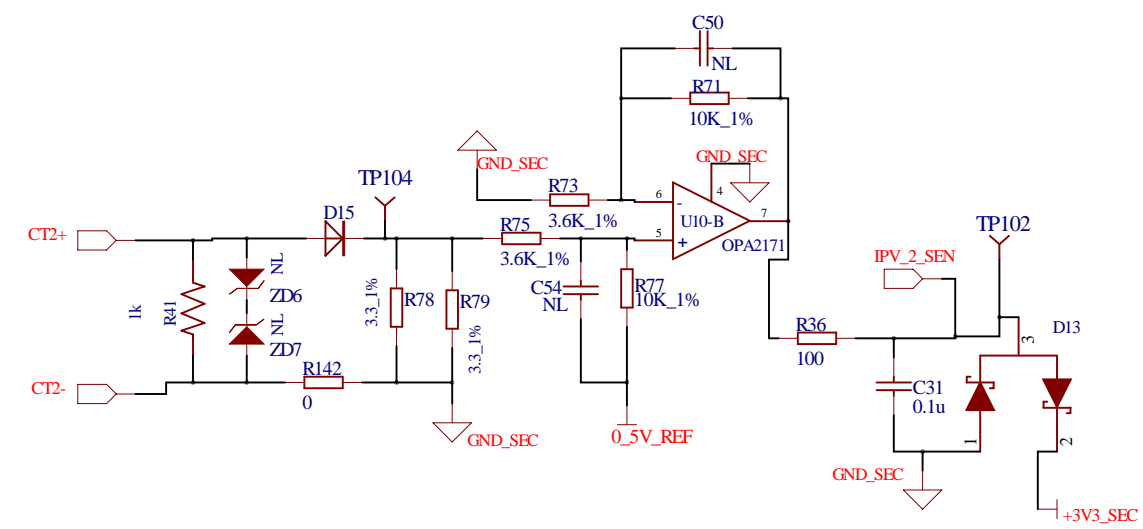
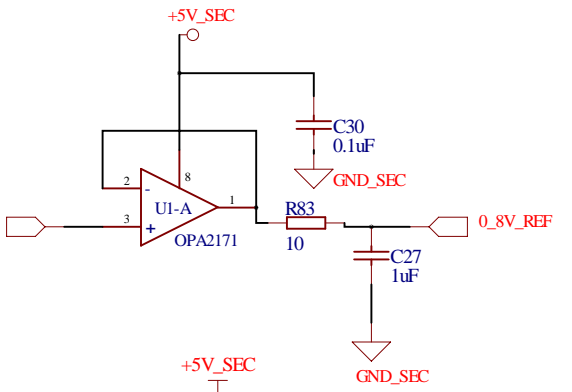
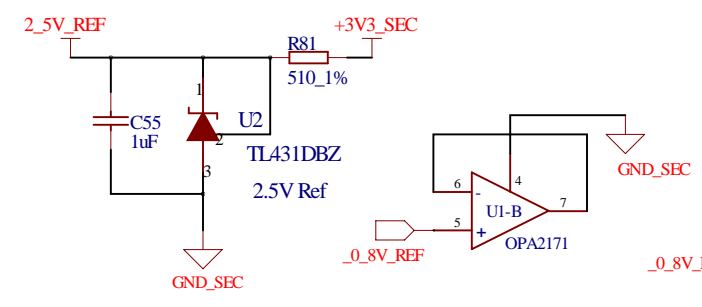


PV Input Voltage Sense (Isolated)

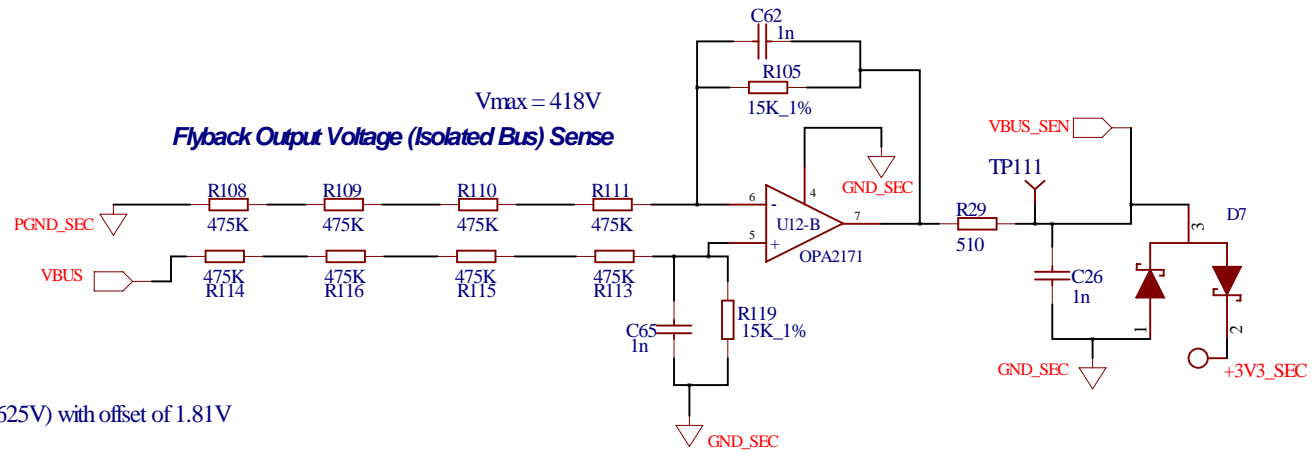
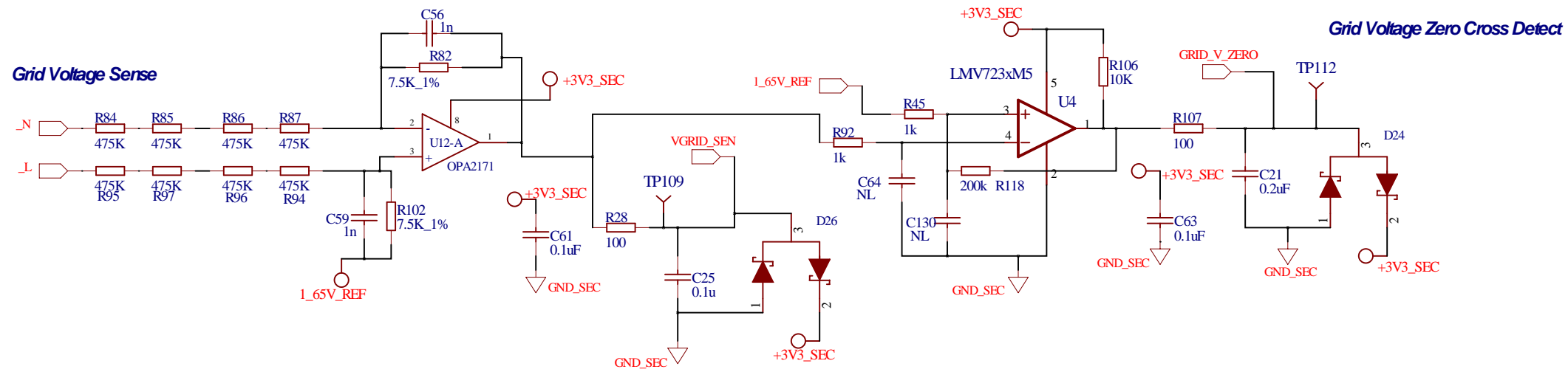


Primary MOSFET Current Sense

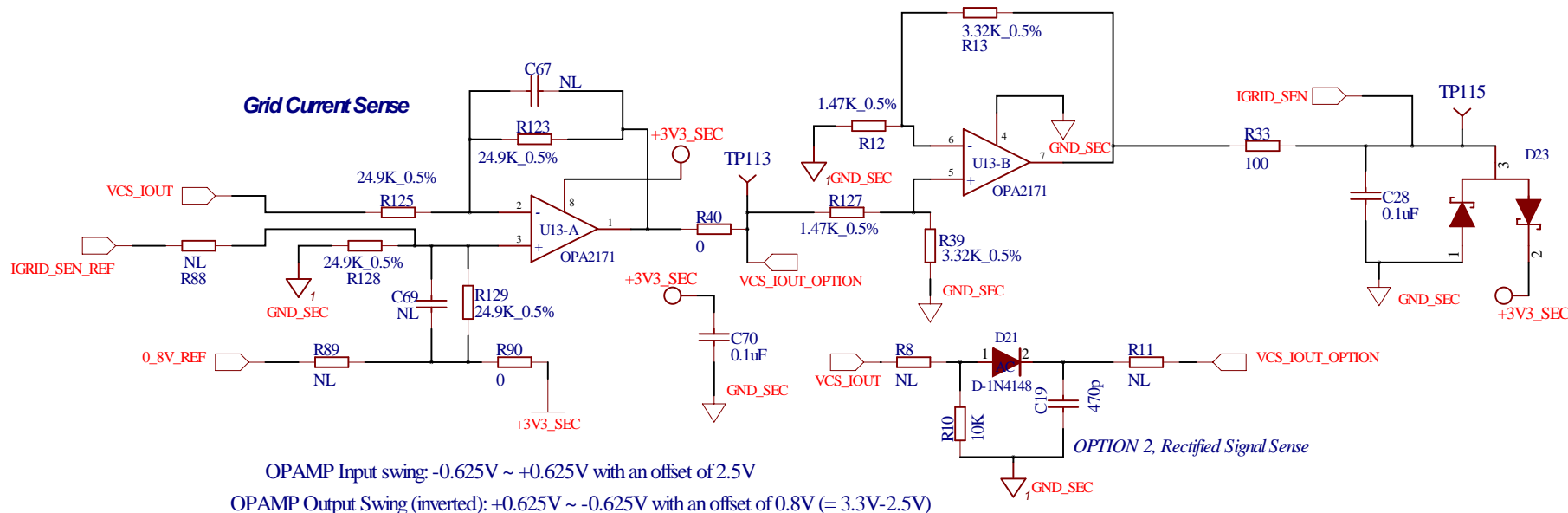


Ref Voltages: 2.5V, 1.65V, 0.8V and 0.5V

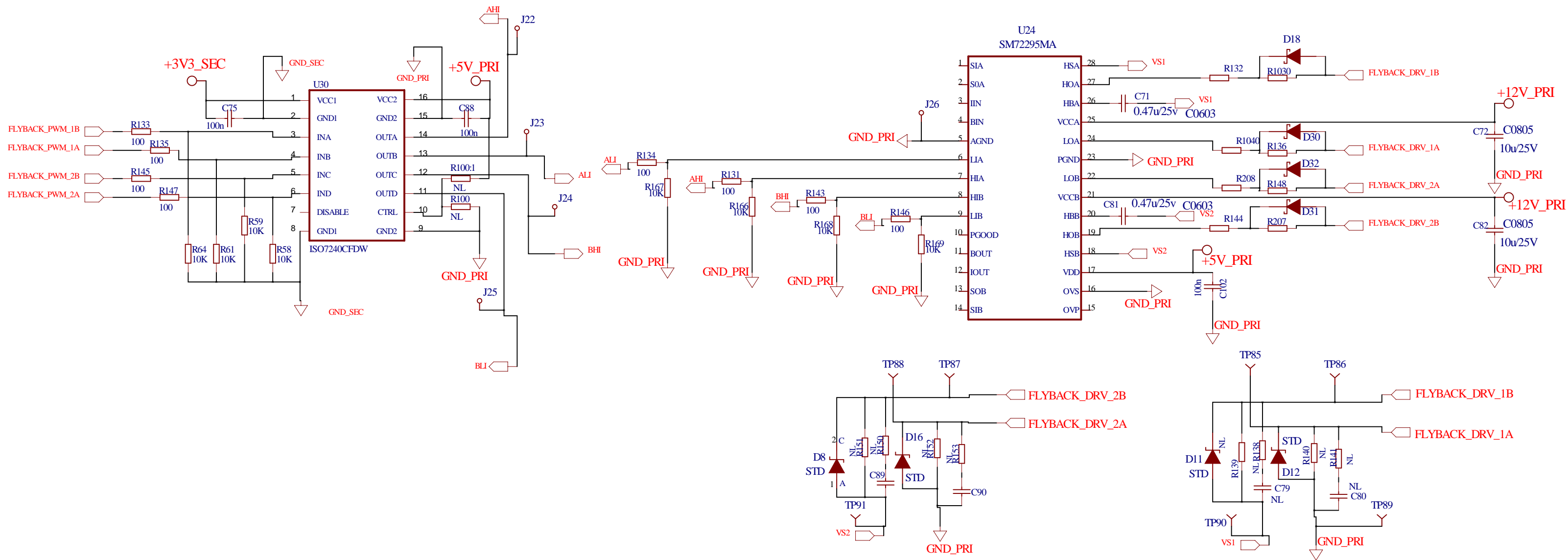
Title: Micro Solar Inverter		
Page Contents: Signal Conditioning 3 & Vref		
Size: B	Signal Conditioning & Vref	Revision: 3.0
Date: 04-04-12	Sheet 1 of 9	



OPAMP Output Swing :  $G \cdot (+0.625V \sim -0.625V)$  with offset of 1.81V  
 Gain  $G = R13/R12$   
 Output Swing :  $+1.41V \sim -1.41V$  with offset of 1.81V



Title: <b>Micro Solar Inverter</b>		
Page Contents: <b>Signal Conditioning 2</b>		
Size: <b>B</b>	Signal Conditioning	Revision: <b>3.0</b>
Date: <b>04-04-12</b>	Sheet <b>2</b> of <b>9</b>	

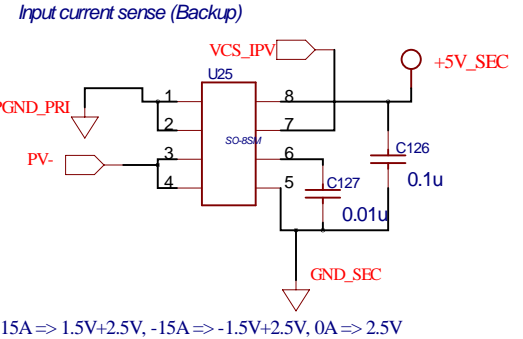
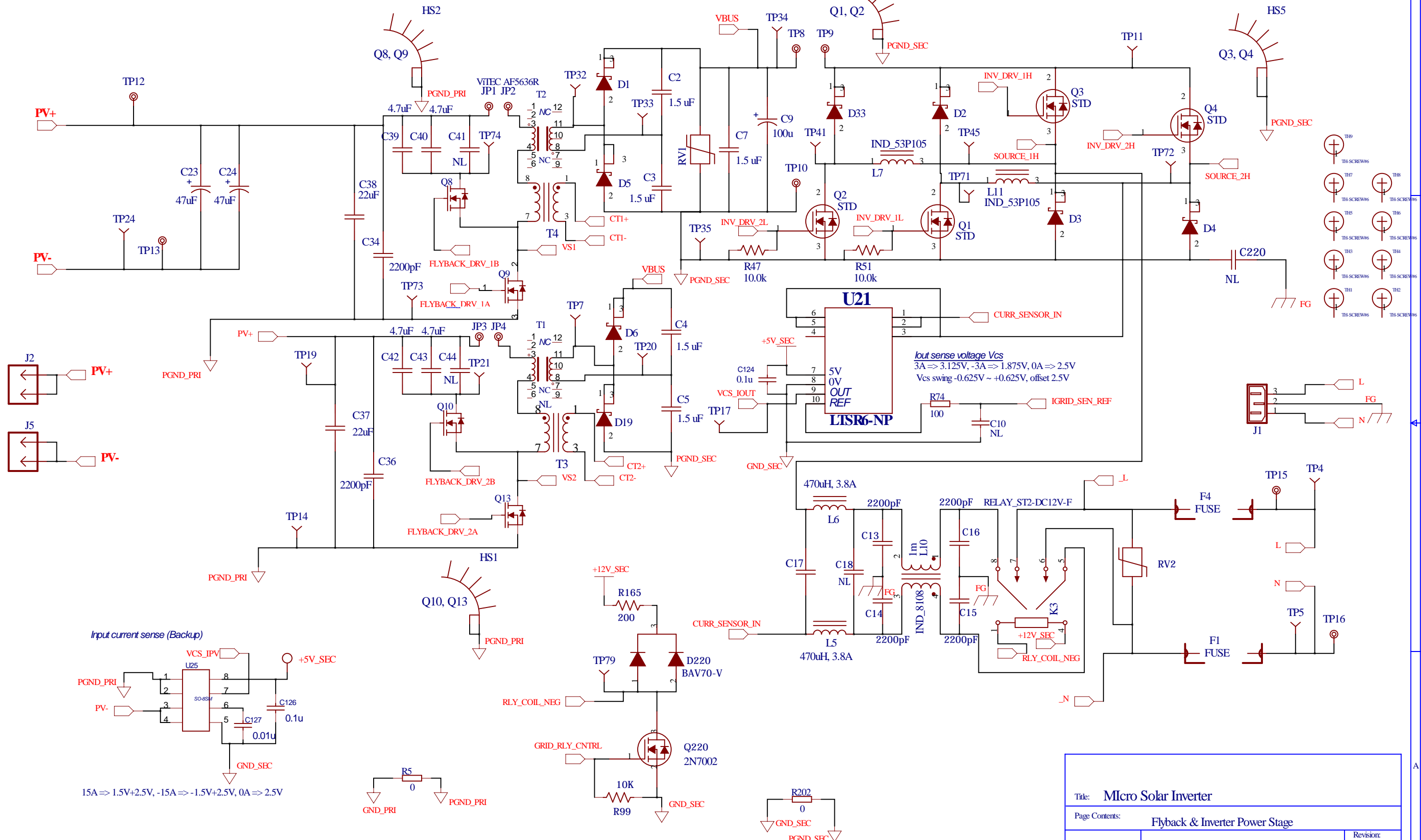


Title: <b>Micro Solar Inverter</b>			Revision: 3.0
Page Contents: <b>Flyback Stage Gate Drive</b>			
Size: <b>B</b>	Flyback Gate Drive		
Date: 04-04-12	Sheet <b>3</b> of <b>9</b>		

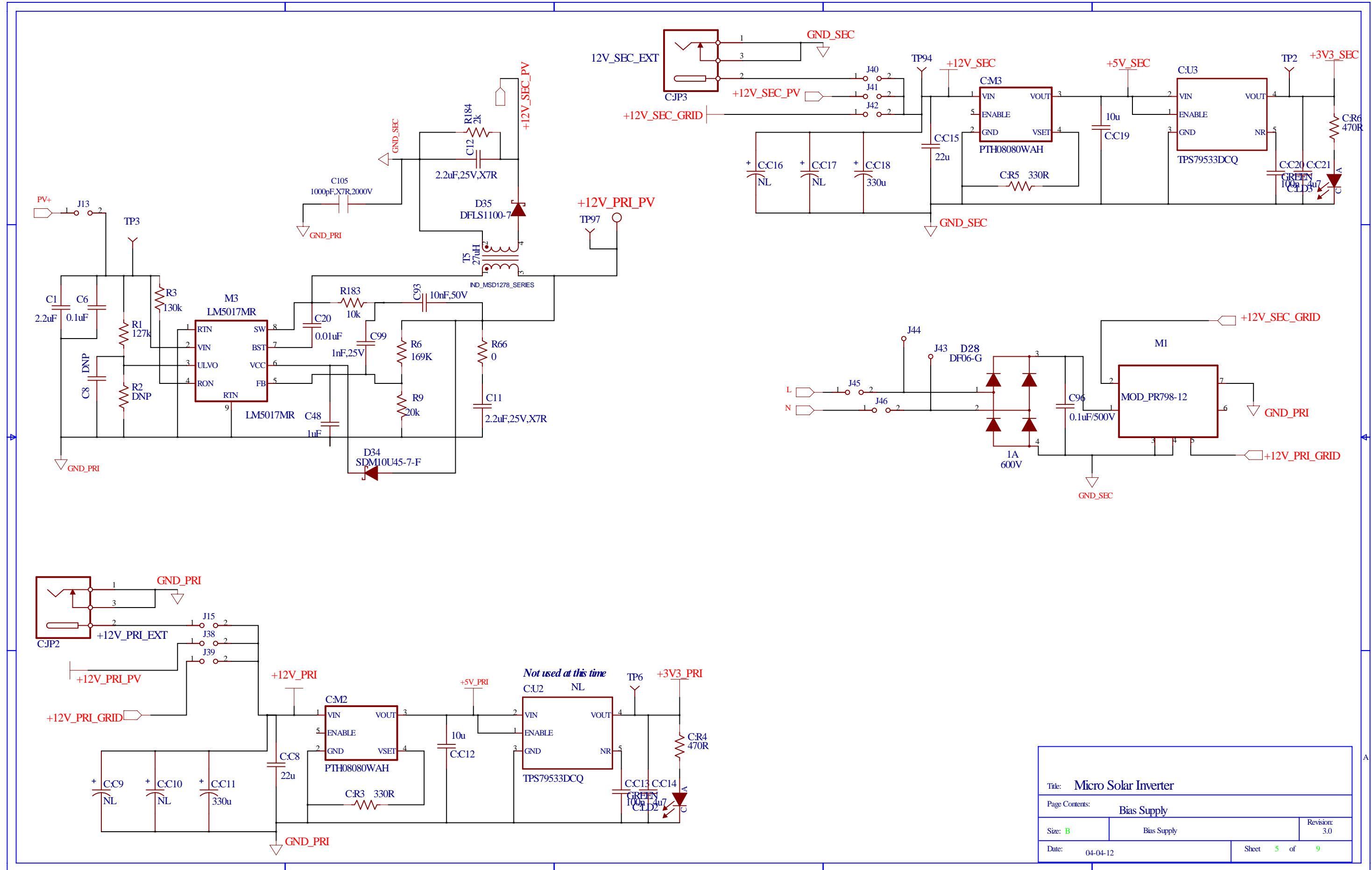
A

Primary Clamped Flyback Power Stage

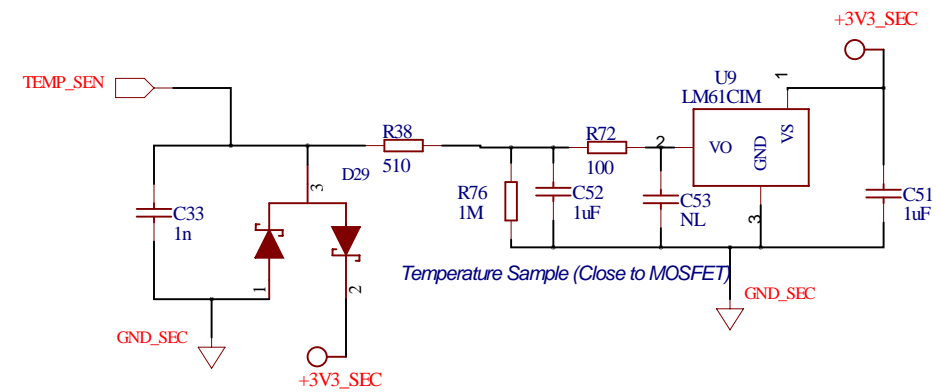
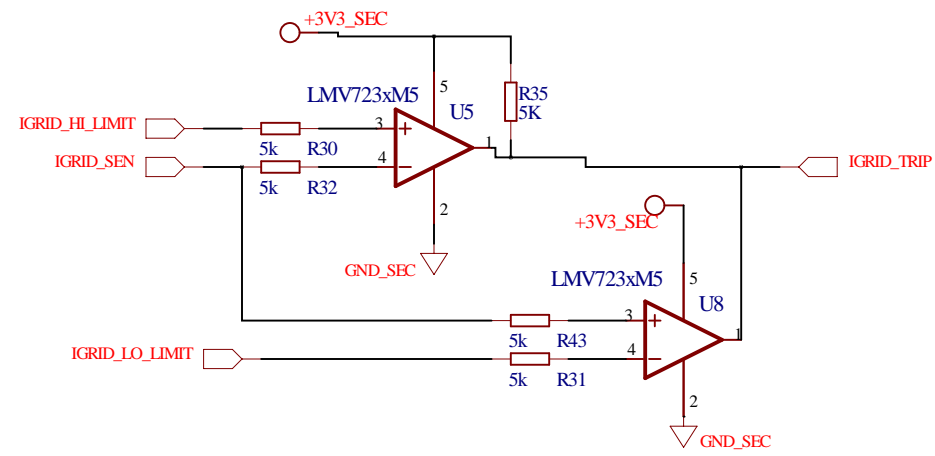
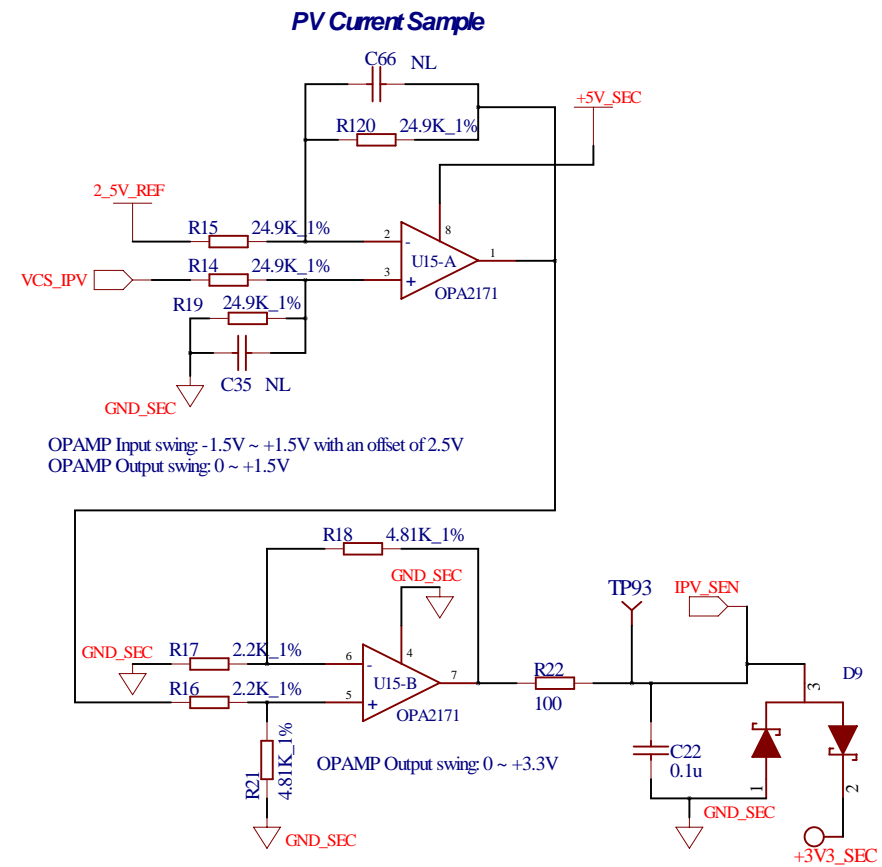
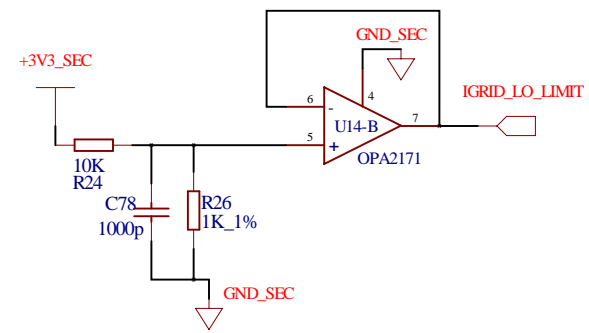
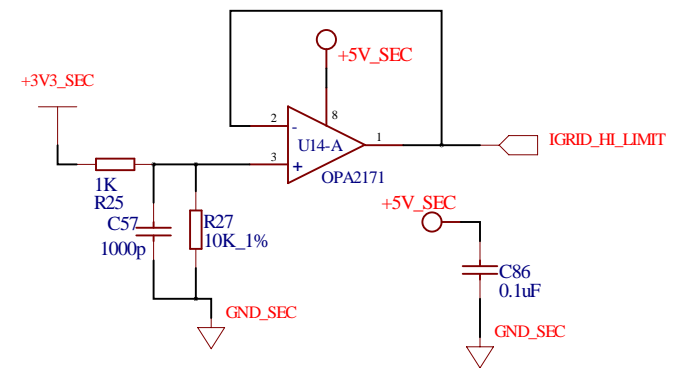
Inverter Power Stage



Title: <b>Micro Solar Inverter</b>		
Page Contents: <b>Flyback &amp; Inverter Power Stage</b>		
Size: <b>B</b>	Power Stage	Revision: <b>3.0</b>
Date: <b>04-04-12</b>	Sheet <b>4</b> of <b>9</b>	

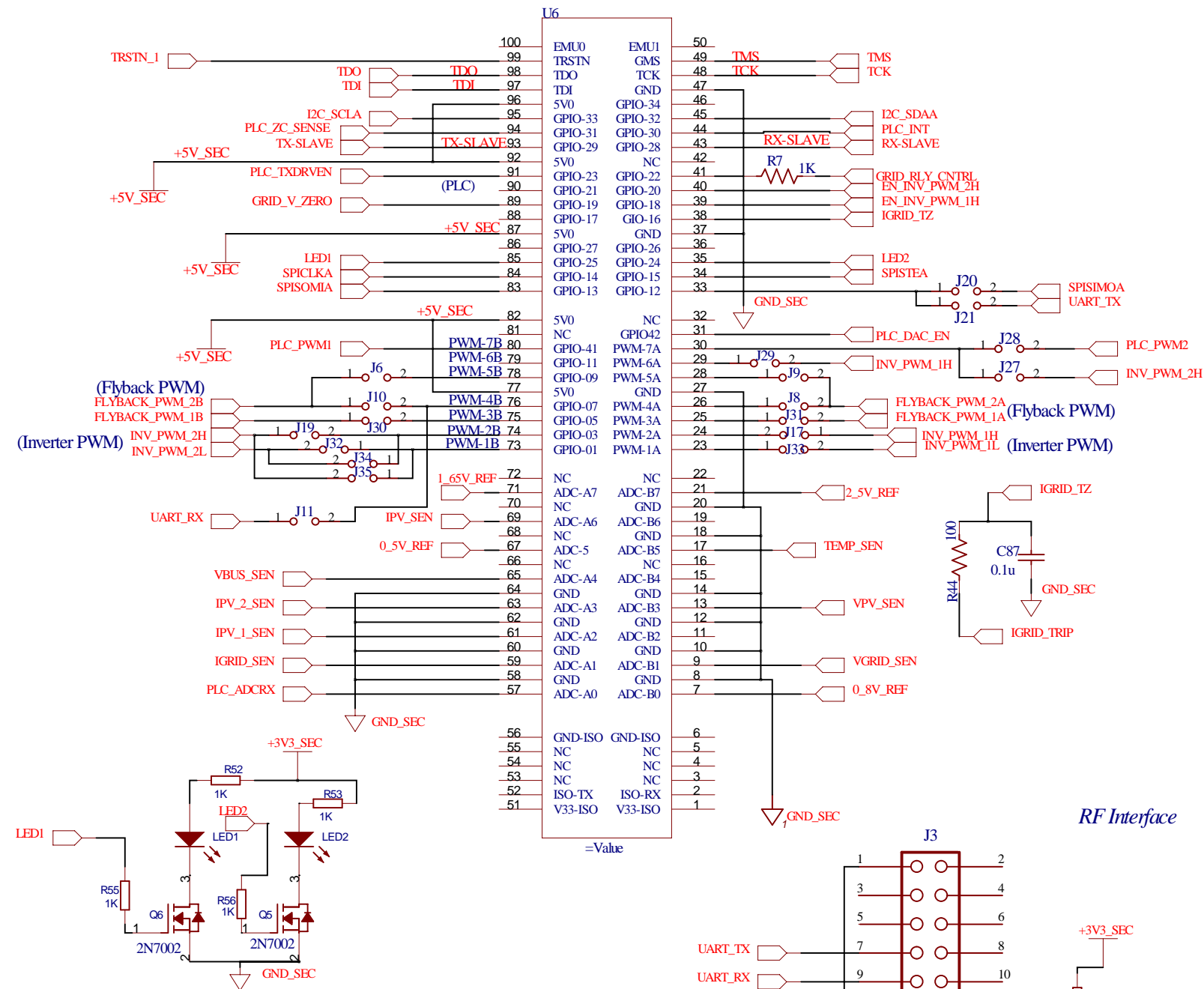


Title: Micro Solar Inverter			
Page Contents: Bias Supply			
Size: B	Bias Supply	Revision: 3.0	
Date: 04-04-12	Sheet 5 of 9		

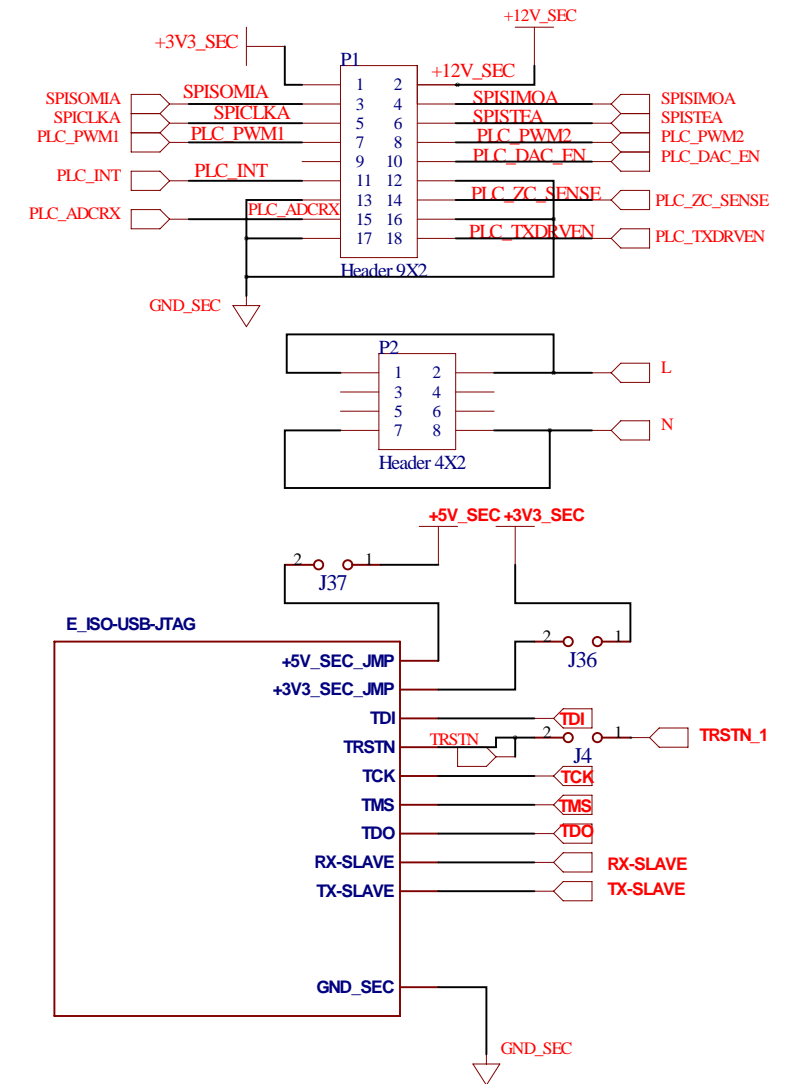


Title: Micro Solar Inverter		
Page Contents: Signal Conditioning 1		
Size: B	Signal Conditioning	Revision: 2.0
Date: 04-04-12	Sheet 6 of 9	

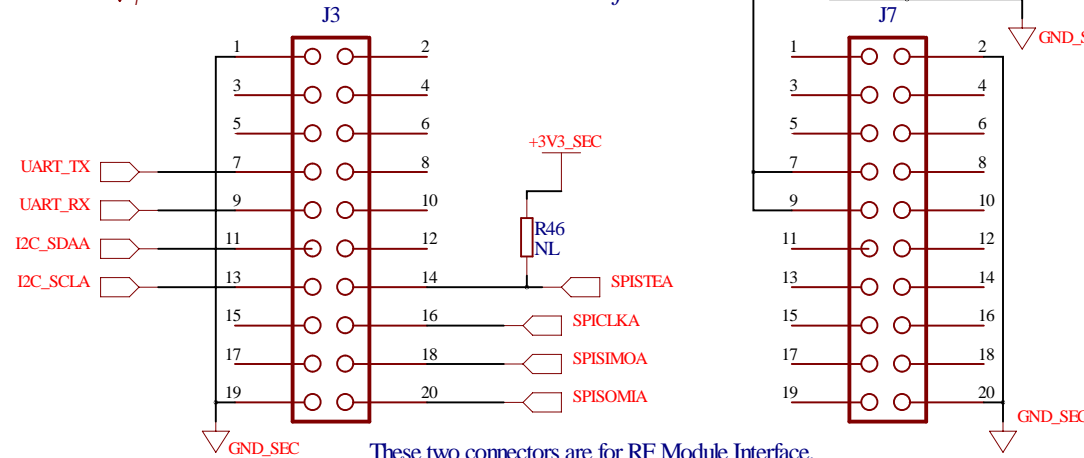
Piccolo Interface



PLC Interface

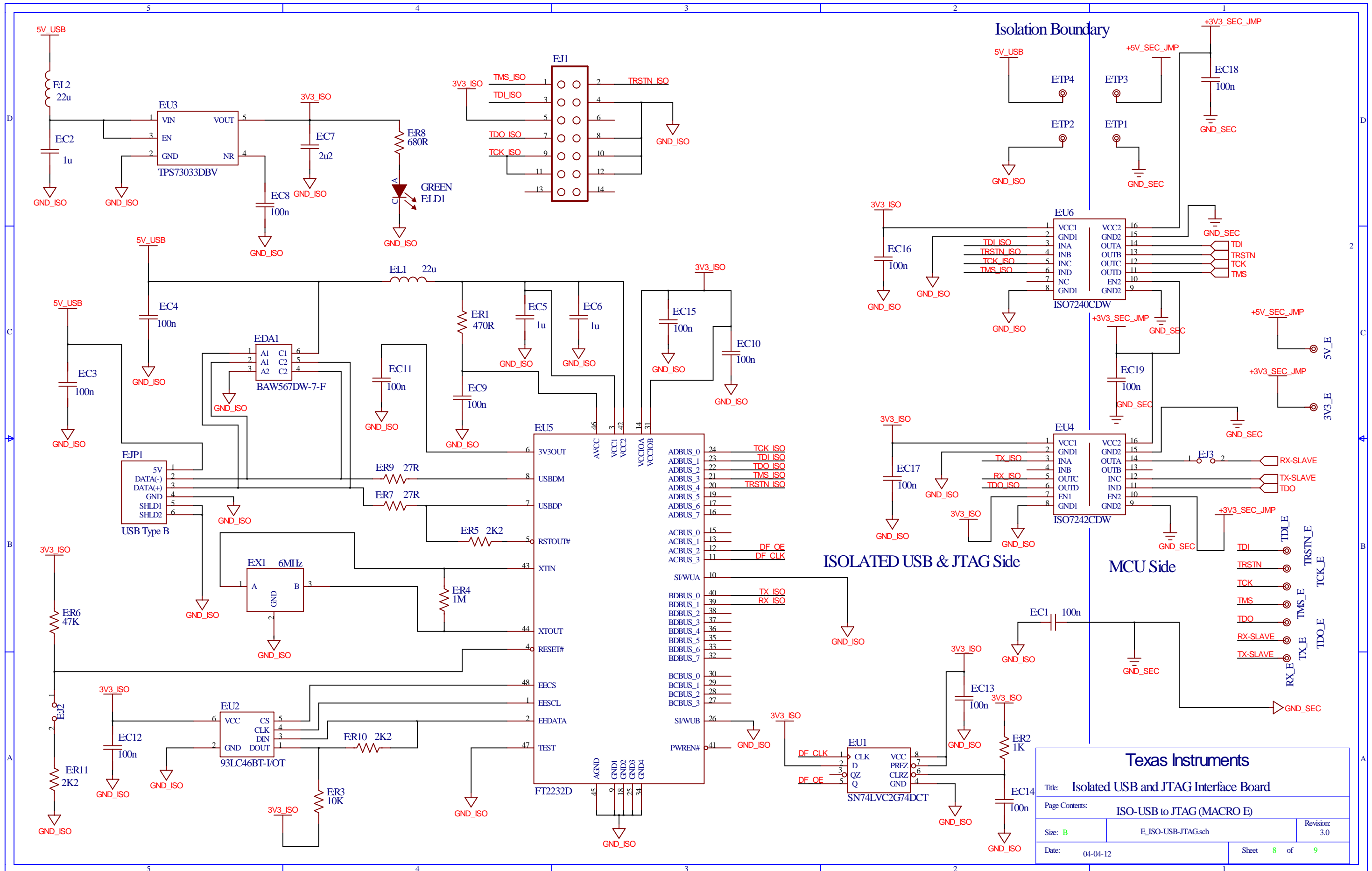


RF Interface



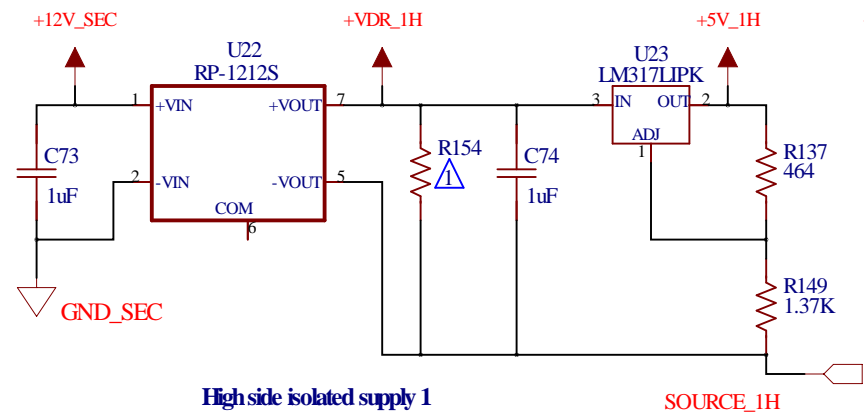
These two connectors are for RF Module Interface. Dimensions must meet spec for interface module CC2530-EVM-UG

Title: <b>Micro Solar Inverter</b>		
Page Contents: <b>Control Card, PLC &amp; RF Interface</b>		
Size: <b>B</b>	Control, PLC & RF	Revision: 3.0
Date: 04-04-12	Sheet <b>7</b> of <b>9</b>	



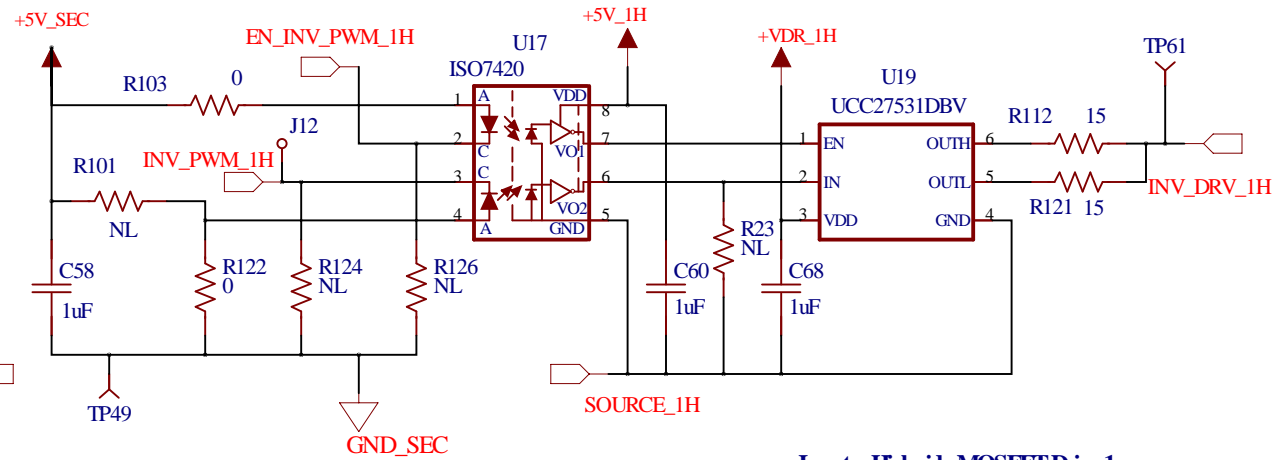
Texas Instruments		
Title: Isolated USB and JTAG Interface Board		
Page Contents: ISO-USB to JTAG (MACRO E)		
Size: B	E_ISO-USB-JTAG.sch	Revision: 3.0
Date: 04-04-12	Sheet 8 of 9	



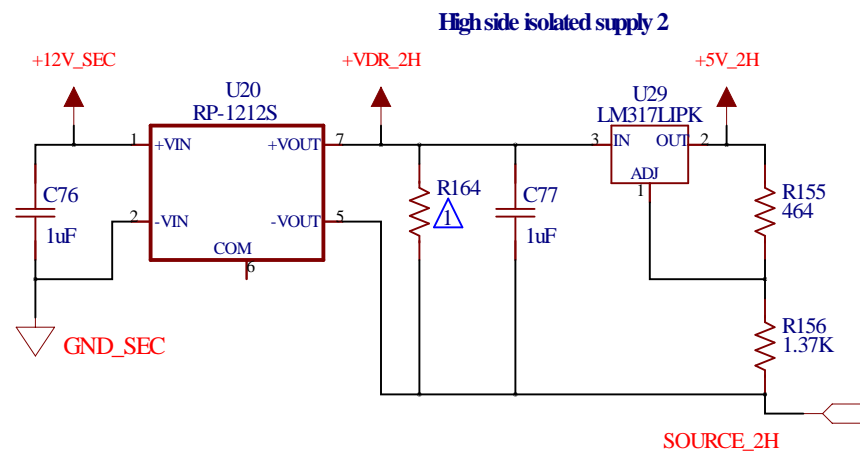


High side isolated supply 1

SOURCE\_1H

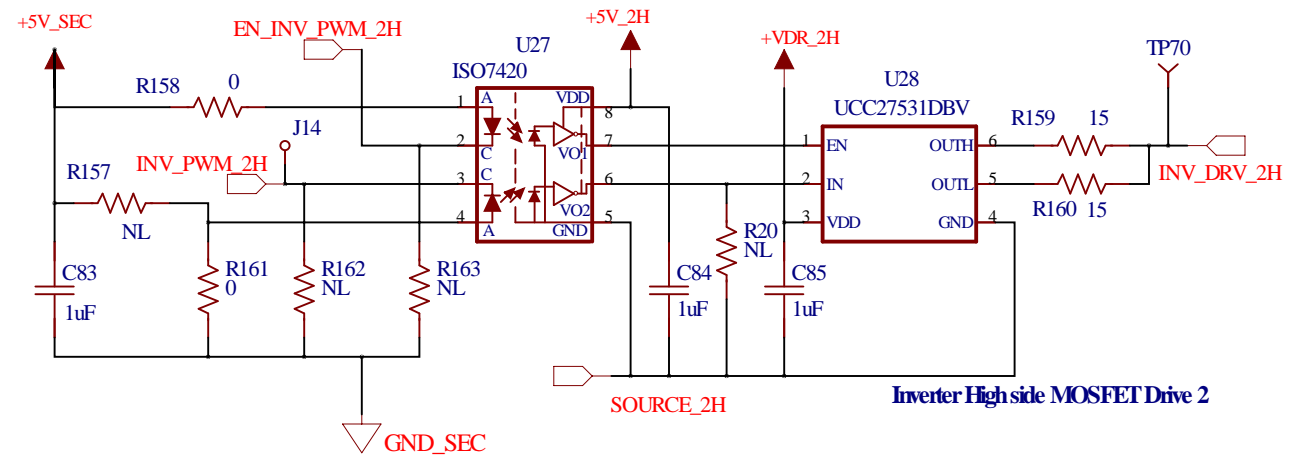


Inverter High side MOSFET Drive 1

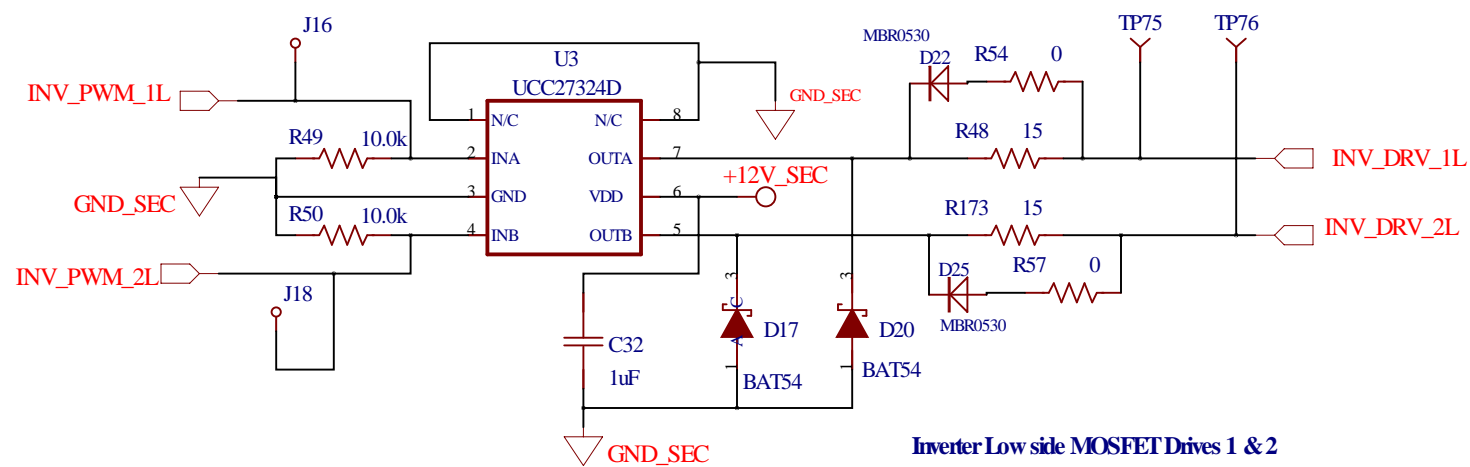


High side isolated supply 2

SOURCE\_2H



Inverter High side MOSFET Drive 2



Inverter Low side MOSFET Drives 1 & 2

Title: Micro Solar Inverter		
Page Contents: Inverter Gate Drive		
Size: B	Inverter Gate Drive	Revision: 3.0
Date: 11-10-12	Sheet 9 of 9	

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